



# HT772

PNP EPITAXIAL PLANAR TRANSISTOR

## Description

The HT772 is designed for using in output stage of 1w audio amplifier, voltage regulator, DC-DC converter and relay driver.

## Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures  
Storage Temperature ..... -55 ~ +150 °C  
Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation  
Total Power Dissipation (Ta=25°C) ..... 1 W  
Total Power Dissipation (Tc=25°C) ..... 10 W
- Maximum Voltages and Currents  
BVCBO Collector to Base Voltage ..... -40 V  
BVCEO Collector to Emitter Voltage ..... -30 V  
BVEBO Emitter to Base Voltage ..... -5 V  
IC Collector Current (DC) ..... -3 A  
IC Collector Current (Pulse) ..... -7 A  
IB Base Current (DC) ..... -0.6 A

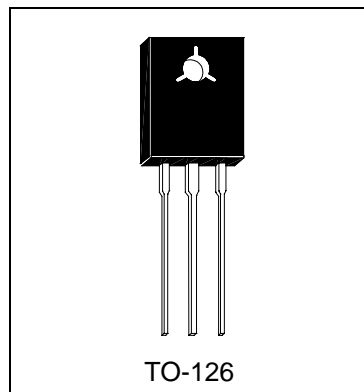
## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-40	-	-	V	IC=-100uA
BVCEO	-30	-	-	V	IC=-1mA
BVEBO	-5	-	-	V	IE=-10uA
ICBO	-	-	-1	uA	VCB=-30V
IEBO	-	-	-1	uA	VEB=-3V
*VCE(sat)	-	-0.3	-0.5	V	IC=-2A, IB=-0.2A
*VBE(sat)	-	-1	-2	V	IC=-2A, IB=-0.2A
*hFE1	30	-	-		IC=-20mA, VCE=-2V
*hFE2	100	200	400		IC=-1A, VCE=-2V
fT	-	80	-	MHz	IC=-0.1A, VCE=-5V
Cob	-	55	-	pF	VCB=-10V, f=1MHz, IE=0

\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

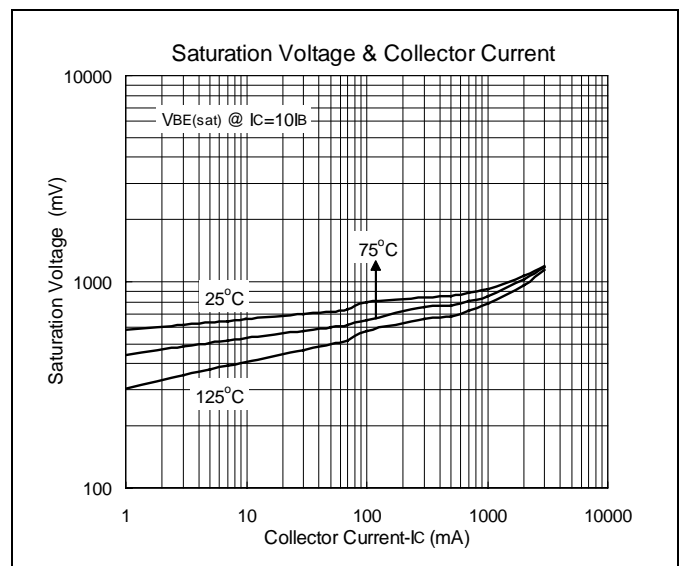
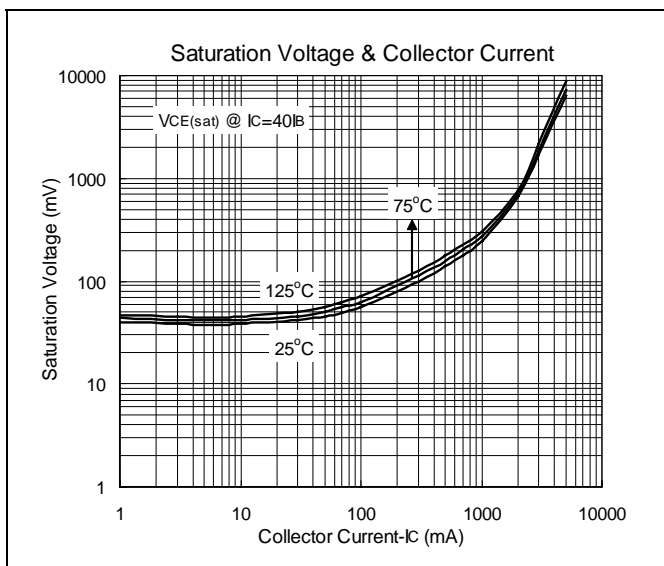
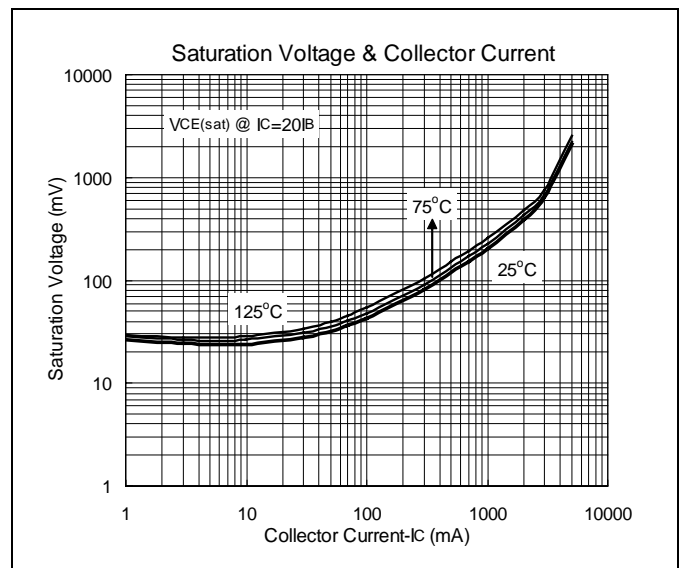
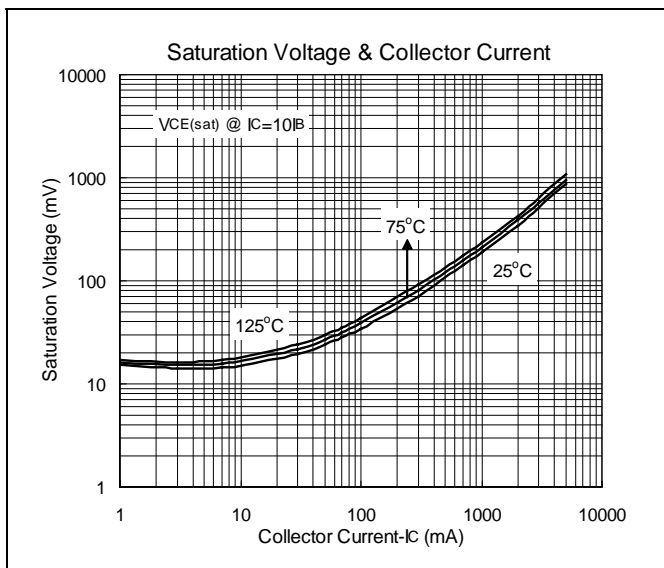
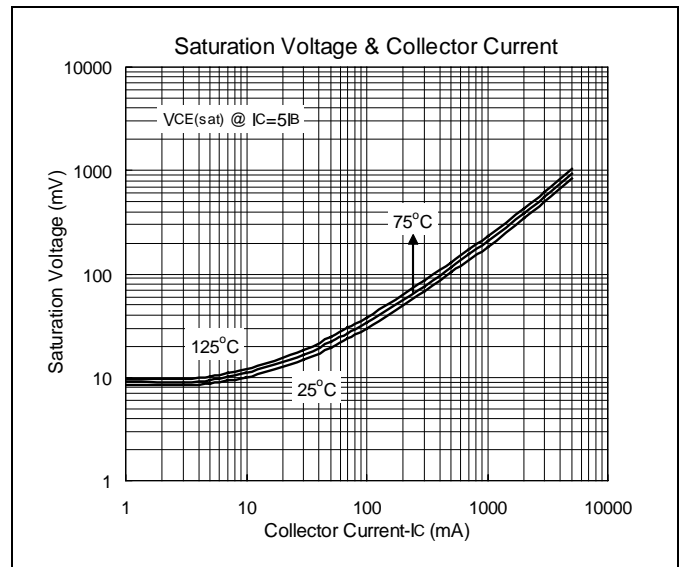
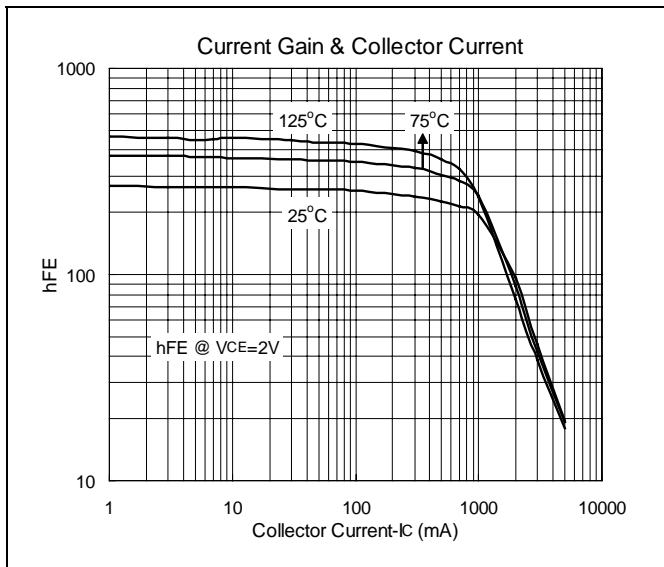
## Classification Of hFE2

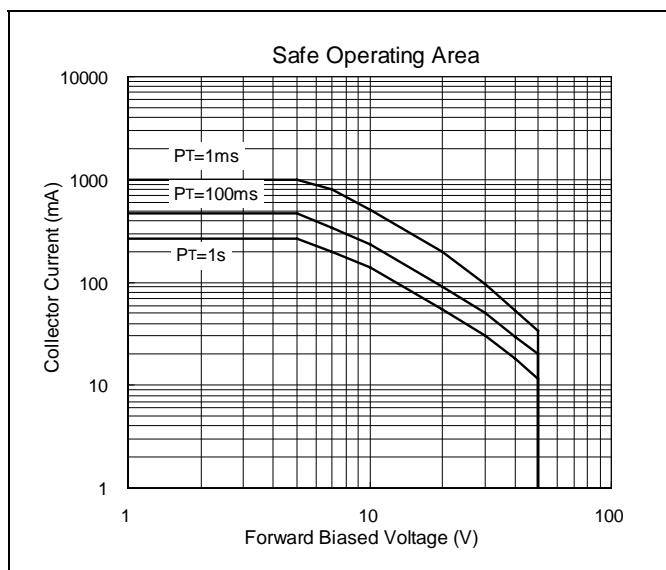
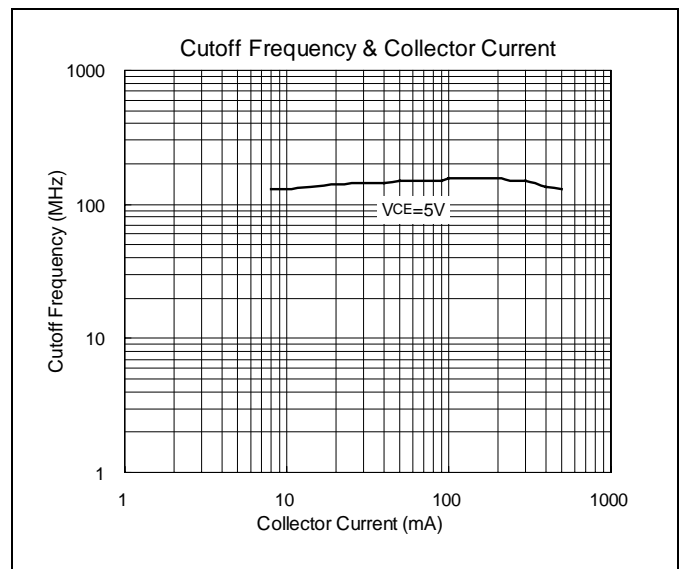
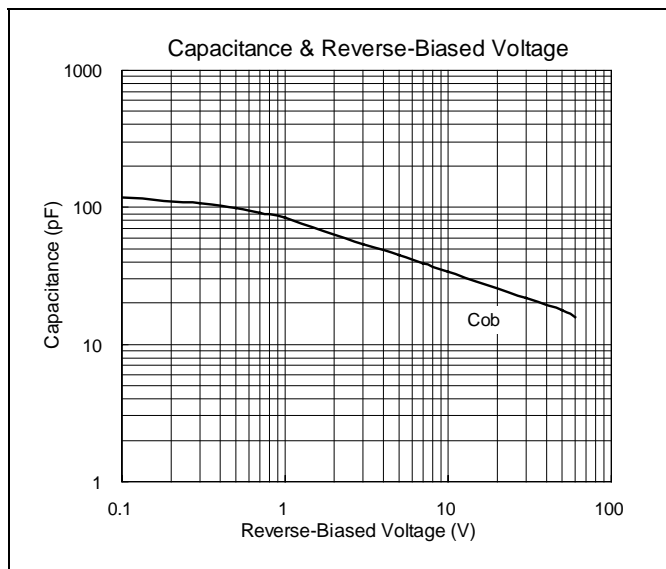
Rank	Q	P	E
Range	100-200	160-320	200-400





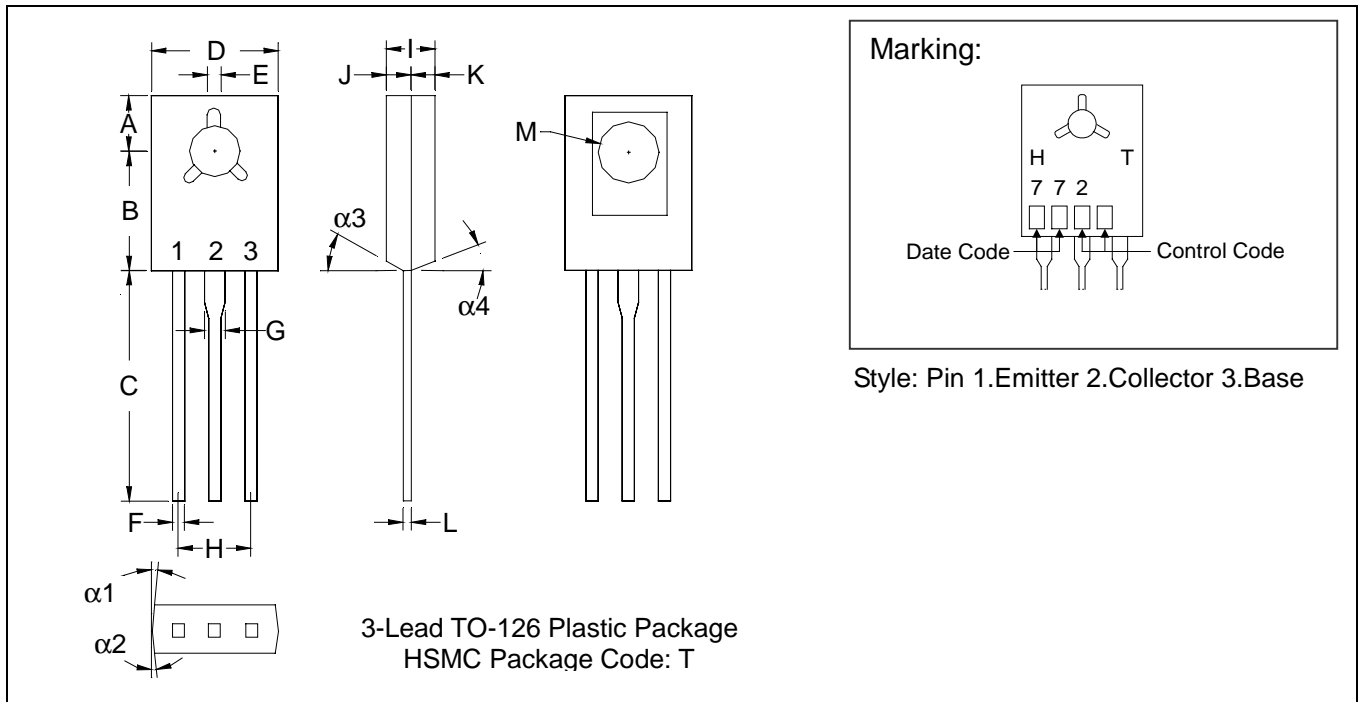
### Characteristics Curve







### TO-126 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
$\alpha 1$	-	*3°	-	*3°	F	0.0280	0.0319	0.71	0.81
$\alpha 2$	-	*3°	-	*3°	G	0.0480	0.0520	1.22	1.32
$\alpha 3$	-	*3°	-	*3°	H	0.1709	0.1890	4.34	4.80
$\alpha 4$	-	*3°	-	*3°	I	0.0950	0.1050	2.41	2.66
A	0.1500	0.1539	3.81	3.91	J	0.0450	0.0550	1.14	1.39
B	0.2752	0.2791	6.99	7.09	K	0.0450	0.0550	1.14	1.39
C	0.5315	0.6102	13.50	15.50	L	-	*0.0217	-	*0.55
D	0.2854	0.3039	7.52	7.72	M	0.1378	0.1520	3.50	3.86
E	0.0374	0.0413	0.95	1.05					

Notes: 1.Dimension and tolerance based on our Spec. dated Mar. 6,1995.

2.Controlling dimension: millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

#### Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

#### Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

#### Head Office And Factory:

• **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F., No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.  
Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454

• **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C  
Tel: 886-3-5983621~5 Fax: 886-3-5982931